

Viscom and CyberOptics Announce Cooperation Agreement for 3D Solder Paste Inspection Sensor Technology

Hannover and Minneapolis, March 17, 2011 – Viscom AG, Hannover, Germany, and CyberOptics Inc., Minneapolis, MN, USA, jointly announce an OEM agreement to equip Viscom's SPI inspection systems product line with CyberOptics' 3D SPI sensor technology. The development and supply agreement allows for the integration of CyberOptics SE500 sensor technology into the Viscom PCB inspection platforms. Viscom's S3088 SPI with the CyberOptics SE500 sensor will be shown at the upcoming IPC APEX 2011 show in Las Vegas, the SMT show in Nuremberg and at Nepcon Shanghai.

With the growing demand for high-end 3D solder paste inspection, Viscom and CyberOptics have determined that their combined technologies create a perfect fit in completing Viscom's product line. CyberOptics has an established 3D SPI technology leadership reputation in the SMT market with over 3000 3D SPI systems sold. Viscom reflects 25 years of providing several thousand high-end AOI and AXI solutions to an established worldwide customer base especially in the automotive and industrial electronics market. The partnership of these two strong players allows access to the growing global SPI needs of important market segments.

The cooperation with CyberOptics puts Viscom into a position to provide a high-speed 3D solder paste inspection system to Viscom's core market and to open new market segments. Volker Pape, co-founder of Viscom, states "We thoroughly analyzed the market for 3D sensor technology and discovered that CyberOptics sensor technology and engineering resources as well as their management experience in handling OEM sensor projects could provide the best matching solution for Viscom's demanding product requirements." He also states "The strategic partnership offers the best solution to our customer base. It perfectly fits into our elaborated system and software structure and gives us the capability to adapt to the highest demands in the market."

"This partnership follows CyberOptics strong tradition of supplying both OEM sensing solutions to leading SMT equipment vendors and to supply inspection solutions direct to customers in the SMT market", said Kitty Iverson, CyberOptics CEO. "This partnership signifies an important milestone in the resurgence of CyberOptics as a leader provider of innovative and advanced SMT sensing solutions to the market."

The first available Viscom solution with the CyberOptics SE500 sensor head is the **Viscom S3088 SPI**. "Integration work was fast and easy, as our software offers all the features needed to evaluate a 3D sensor signal and to easily generate inspection programs. It took less than three months from start of integration to a full speed running prototype" Peter Krippner, head of Viscom serial product division mentioned. "It gives the results we expected and fits perfectly to our elaborated system platform. After the field test phase has finished, production rollout of the Viscom S3088 SPI with CyberOptics SE500 sensor head will start in June 2011."

"We are extremely excited about this additional OEM partnership with Viscom, it is a unique opportunity to add to both Companies' product portfolios", Kitty Iverson added.

About CyberOptics

Founded in 1984, CyberOptics Corporation is a leading provider of sensors and inspection systems that provide process yield and through-put improvement solutions for the global electronic assembly and semiconductor capital equipment markets. Our products are deployed on production lines that manufacture surface mount technology circuit boards and semiconductor process equipment. By increasing productivity and product quality, our sensors and inspection systems enable electronics manufacturers to strengthen their competitive positions in highly price-sensitive markets. Headquartered in Minneapolis, Minnesota, we conduct worldwide operations through facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: market conditions in the global SMT and semiconductor capital equipment industries; the need for a valuation allowance with respect to our deferred tax assets; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required for meeting customer orders; the effect of world events on our sales, the majority of which are from foreign customers; product introductions and pricing by our competitors; the level of revenue and profitability we achieve in 2011; success of anticipated new OEM and end-user opportunities and other factors set forth in the Company's filings with the Securities and Exchange Commission.

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